

04-20-2006

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Atty Docket #:
ONS00647



103223118

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new application(s) below.

1. Name of conveying party(ies):

**Shutesh Krishnan
Jatinder Kumar**

Additional name(s) of conveying party(ies) is provided on attached sheet?

Yes ☐ No ☒

3. Nature of conveyance/Execution Date(s):

Execution Date(s) **December 19, 2005**

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other _____

2. Name and address of receiving party(ies):

NAME:
SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C.
Internal Address: **Law Department - A700**

Street Address: **5005 East McDowell Road**

City: **Phoenix**

State: **Arizona**

Country: **USA** Zip: **85008**

Additional name(s) & address(es) attached? Yes ☐ No ☒

113374 U.S. PTO
11/403978
041406

4. Application number(s) or patent number(s):

A. Patent Application No.(s):

☒ This document is being filed together with a new application.

B. Patent No.(s):

Additional numbers attached? ☐ Yes No ☒

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **SEMICONDUCTOR COMPONENTS INDUSTRIES, L.L.C.**

Internal Address: **Patent Administration - A700**

Street Address: **P. O. Box 62890**

City, State, Zip: **Phoenix, Arizona 85082-2890**

Phone Number: **602-244-5358**

Fax Number: **602-244-3169/602-244-5601**

Email Address: **Brad.Botsch@onsemi.com**

6. Total number of applications and patents involved: **1**

7. Total fee (37 C.F.R. 3.41) **\$40.00**

☐ Enclosed

☒ Authorized to be charged to deposit account

8. Payment Information

Deposit account number: **501086**

Authorized User Name: **Kevin B. Jackson**

9. Signature.

Kevin B. Jackson

Name of Person Signing

Signature

April 12, 2006

Date

Total number of pages including cover sheet, attachments, and document: **2**

11/3/2005 08:55:00 00000001 501086 11/403978

PT1595-01

(40,000 DA)

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

PATENT
REEL: 017792 FRAME: 0517

**ASSIGNMENT OF ENTIRE INTEREST IN INVENTION
BEFORE THE ISSUE OF LETTERS PATENT**

Whereas, the undersigned have invented an invention entitled
SEMICONDUCTOR PACKAGE STRUCTURE AND METHOD OF MANUFACTURE
(Attorney Docket No. ONS00647
for which we make application for letters patent in Malaysia; and

Whereas,
SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C., (SCI), a Limited Liability Company of the
State of Delaware, United States of America, having a principal place of business at 5005 E. McDowell Road,
Phoenix, Arizona 85008 , United States of America, is desirous acquiring the said invention and the patent
thereto:


Now, therefore, for valuable consideration receipt of which is hereby acknowledged, we by these
presents, do sell, assign, and transfer unto SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C. the full and
exclusive right in and to the said invention, as described in the specification executed by us preparatory to
obtaining letters patent in Malaysia therefor; said invention, application, and letters patent to be held and enjoyed
by the said unto SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C. for its own use and behalf and for its
legal representatives, to the full end of the term for which said letters patent may be granted, as fully and entirely
as the same would have been held by us had this assignment not been made.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the
invention and in and to applications for Letters Patent therefor in all countries foreign to Malaysia, including all
rights under any and all international conventions and treaties in respect of the inventions and the applications for
Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries
directly in its own name, and to claim the priority of the filing date of the application for Letters priority of the filing
date of the application for Letters Patent of Malaysia under the provisions of any and all international conventions
and treaties.

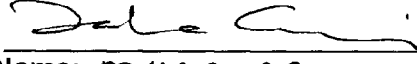
We hereby authorize and request the Patent Office to issue Letters Patent upon the aforesaid application,
division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns,
and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as
they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and
request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI. We
agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful
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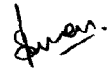
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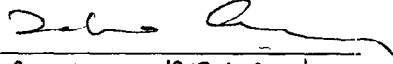
Shutesh Krishnan
77, TAMAN ENGGANG ,MUAR, JOHOR
MALAYSIA 84000
Date: 19/12/05

Witnessed by: 

Name: ARTHAR ARPIN
Date: 19/12/2005



Jatinder Kumar
306, NEW ABADI JALLOWAL ,P/O BOOTAN MANDI
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INDIA 144003
Date: 19/12/05

Witnessed by: 

Name: ARTHAR ARPIN
Date: 19/12/2005